

In the claims:

1-32 (canceled)

33. (previously presented) An apparatus for polishing a wafer comprising:
a polishing pad having a surface and a first wear rate during polishing;
a window portion formed in the polishing pad and having a surface formed flush with the
polishing pad surface; and
wherein the window portion has a second wear rate during polishing equal to or greater
than the first wear rate so that the window surface remains flush with the polishing pad surface
during polishing.

34. (previously presented) The apparatus of claim 33, wherein the second wear rate is 5% to
25% greater than the first wear rate.

35. (previously presented) The apparatus of claim 33, wherein the window portion includes a
polymerized blend of two immiscible polymers.

36. (previously presented) The apparatus of claim 33, wherein the window portion includes at
least one of polymethylmethacrylate and polycarbonate.

37. (previously presented) The apparatus of claim 33, wherein the window portion includes a
polymer matrix having discontinuities formed therein that act to increase the wear rate of the
polymer matrix without significantly contributing to light scattering.

38. (previously presented) The apparatus of claim 37, wherein the discontinuities include at least
one selected from the group of discontinuities comprising: solid particles, fluids, gases and
immiscible polymers.

39. (previously presented) The apparatus of claim 37, wherein the discontinuities include solid
matter having a lower resistance to wear than the polymer matrix.

40. (previously presented) The apparatus of claim 39, wherein the solid matter includes at least one type of solid particles selected from the group of particles comprising: silica, titania, alumina, ceria, and plastic.

41. (canceled)

42. (canceled)

43. (canceled)

44. (canceled)

45. (new) A polishing pad for chemical mechanical polishing a semiconductor wafer comprising:
a polishing surface having a first wear rate during polishing;
a window portion formed in the polishing pad and having a window surface formed flush with the polishing surface; and
wherein the window surface has a second wear rate during polishing greater than the first wear rate.

46. (new) The polishing pad of claim 45, wherein the second wear rate is 5% to 25% greater than the first wear rate.

47. (new) The polishing pad of claim 45, wherein the window portion includes a polymerized blend of two immiscible polymers.

48. (new) The polishing pad of claim 45, wherein the window portion includes at least one of polymethylmethacrylate and polycarbonate.

49. (new) The polishing pad of claim 45, wherein the window portion includes a polymer matrix having discontinuities formed therein that act to increase the wear rate of the polymer matrix without significantly contributing to light scattering.

50. (new) The polishing pad of claim 49, wherein the discontinuities include at least one selected from the group of discontinuities comprising: solid particles, fluids, gases and immiscible polymers.

51. (new) The polishing pad of claim 49, wherein the discontinuities include solid matter having a lower resistance to wear than the polymer matrix.

52. (new) The polishing pad of claim 51, wherein the solid matter includes at least one type of solid particles selected from the group of particles comprising: silica, titania, alumina, ceria, and plastic.